

**Integrated chip package structure using silicon substrate and method of  
manufacturing the same**

Appl. No.	:	10/755,042	Confirmation No. :	8665
Applicant	:	Mou-Shiung Lin et al.		
Filed	:	January 9, 2004		
TC/A.U.	:	2815		
Examiner	:	JACKSON JR, JEROME		
Docket No.	:	MEGP0004USA1		
Customer No.	:	27765		

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**5 AMENDMENT AND REQUEST FOR CONTINUED EXAMINATION**

Sir:

In response to the Office action of January 4, 2008, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2  
10 of this paper.

**Remarks/Arguments** begin on page 10 of this paper.